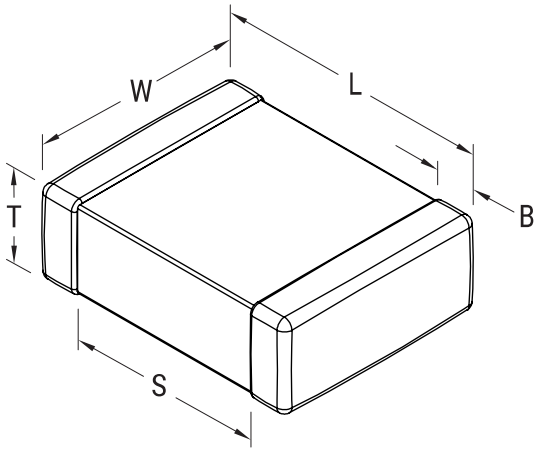
C1206X300JDGACTU

Aliases (C1206X300JDGAC7800)

SMD Comm C0G HV Flex, Ceramic, 30 pF, 5%, 1,000 VDC, C0G, SMD, MLCC, FT-CAP, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm C0G HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
T	1mm +/-0.20mm
S	1.5mm MIN
B	0.6mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

Specifications	
Capacitance	30 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	5%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1,200 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms